

SILICON AND SAPPHIRE WAFER EDGE GRINDING WHEEL

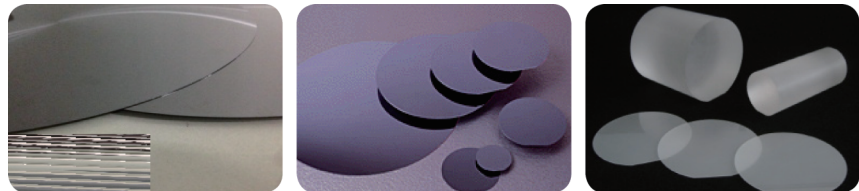


Advantages

- Various groove shapes can be designed.
- Grinded with uniform chamfer width (excellent rigidity)
- Strong groove shape retention.
- Product 1ea enables multi-stage grinding (rough / fine grinding)

Application

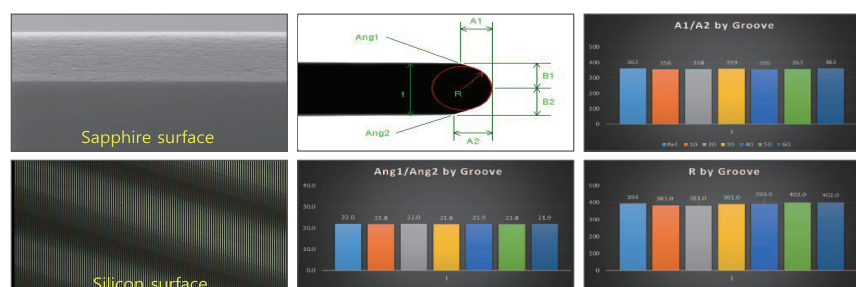
- Silicon and sapphire wafer edge grinding



Available Product Spec.

MD-DW	Φ 3.9	5G	5 ~ 20mm	#325 ~ #3000	5G
MD-1FF6Y	Φ 202	8G	5 ~ 20mm		8G~10G

Performance Data



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